

Table of Contents

| | |
|-------------------------------------------|----|
| Description | 1 |
| Maximum ratings | 3 |
| Thermal characteristics | 3 |
| Electrical characteristics | 4 |
| Electrical characteristics diagrams | 6 |
| Test Circuits | 10 |
| Package Outlines | 11 |
| Appendix A | 13 |
| Revision History | 14 |
| Trademarks | 14 |
| Disclaimer | 14 |

1 Maximum ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 2 Maximum ratings

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|----------------------------------------|---------------|--------|------|----------|------------------|---------------------------------------------------------------------------------------|
| | | Min. | Typ. | Max. | | |
| Continuous drain current ¹⁾ | I_D | - | - | 5 3.2 | A | $T_C=25^\circ\text{C}$ $T_C=100^\circ\text{C}$ |
| Pulsed drain current ²⁾ | $I_{D,pulse}$ | - | - | 8 | A | $T_C=25^\circ\text{C}$ |
| Avalanche energy, single pulse | E_{AS} | - | - | 26 | mJ | $I_D=0.6\text{A}$; $V_{DD}=50\text{V}$; see table 11 |
| Avalanche energy, repetitive | E_{AR} | - | - | 0.09 | mJ | $I_D=0.6\text{A}$; $V_{DD}=50\text{V}$; see table 11 |
| Avalanche current, repetitive | I_{AR} | - | - | 0.6 | A | - |
| MOSFET dv/dt ruggedness | dv/dt | - | - | 50 | V/ns | $V_{DS}=0\dots480\text{V}$ |
| Gate source voltage (static) | V_{GS} | -20 | - | 20 | V | static; |
| Gate source voltage (dynamic) | V_{GS} | -30 | - | 30 | V | AC ($f>1\text{ Hz}$) |
| Power dissipation TO-251, TO252 | P_{tot} | - | - | 49 | W | $T_C=25^\circ\text{C}$ |
| Storage temperature | T_{stg} | -40 | - | 150 | $^\circ\text{C}$ | - |
| Operating junction temperature | T_j | -40 | - | 150 | $^\circ\text{C}$ | - |
| Continuous diode forward current | I_S | - | - | 3.5 | A | $T_C=25^\circ\text{C}$ |
| Diode pulse current ²⁾ | $I_{S,pulse}$ | - | - | 8 | A | $T_C=25^\circ\text{C}$ |
| Reverse diode dv/dt ³⁾ | dv/dt | - | - | 15 | V/ns | $V_{DS}=0\dots400\text{V}$, $I_{SD}\leq I_S$, $T_j=25^\circ\text{C}$ see table 9 |
| Maximum diode commutation speed | di/dt | - | - | 500 | A/ μs | $V_{DS}=0\dots400\text{V}$, $I_{SD}\leq I_S$, $T_j=25^\circ\text{C}$ see table 9 |

2 Thermal characteristics

Table 3 Thermal characteristics TO-251, TO252

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|---------------------------------------------------------------|------------|--------|------|------|--------------------|-------------------------------------|
| | | Min. | Typ. | Max. | | |
| Thermal resistance, junction - case | R_{thJC} | - | - | 2.57 | $^\circ\text{C/W}$ | - |
| Thermal resistance, junction - ambient | R_{thJA} | - | - | 62 | $^\circ\text{C/W}$ | leaded |
| Soldering temperature, wavesoldering only allowed at leads | T_{sold} | - | - | 260 | $^\circ\text{C}$ | 1.6mm (0.063 in.) from case for 10s |

¹⁾ Limited by $T_{j,max}$. Maximum duty cycle $D=0.50$

²⁾ Pulse width t_p limited by $T_{j,max}$

³⁾ Identical low side and high side switch with identical R_G

3 Electrical characteristics

at $T_j=25^\circ\text{C}$, unless otherwise specified

Table 4 Static characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|----------------------------------|---------------|--------|------|------|----------|-------------------------------------------------------------------------------------|
| | | Min. | Typ. | Max. | | |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | 600 | - | - | V | $V_{GS}=0V, I_D=0.25mA$ |
| Gate threshold voltage | $V_{(GS)th}$ | 2.5 | 3.0 | 3.5 | V | $V_{DS}=V_{GS}, I_D=0.09mA$ |
| Zero gate voltage drain current | I_{DSS} | - | - | 1 | μA | $V_{DS}=600, V_{GS}=0V, T_j=25^\circ C$ $V_{DS}=600, V_{GS}=0V, T_j=150^\circ C$ |
| Gate-source leakage current | I_{GSS} | - | - | 100 | nA | $V_{GS}=20V, V_{DS}=0V$ |
| Drain-source on-state resistance | $R_{DS(on)}$ | - | 1.26 | 1.50 | Ω | $V_{GS}=10V, I_D=1.1A, T_j=25^\circ C$ $V_{GS}=10V, I_D=1.1A, T_j=150^\circ C$ |
| Gate resistance | R_G | - | 14 | - | Ω | $f=1MHz, \text{open drain}$ |

Table 5 Dynamic characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|------------------------------------------------------------|--------------|--------|------|------|------|--------------------------------------------------------------------|
| | | Min. | Typ. | Max. | | |
| Input capacitance | C_{iss} | - | 200 | - | pF | $V_{GS}=0V, V_{DS}=100V, f=1MHz$ |
| Output capacitance | C_{oss} | - | 16 | - | pF | $V_{GS}=0V, V_{DS}=100V, f=1MHz$ |
| Effective output capacitance, energy related ¹⁾ | $C_{o(er)}$ | - | 11 | - | pF | $V_{GS}=0V, V_{DS}=0...480V$ |
| Effective output capacitance, time related ²⁾ | $C_{o(tr)}$ | - | 41.3 | - | pF | $I_D=\text{constant}, V_{GS}=0V, V_{DS}=0...480V$ |
| Turn-on delay time | $t_{d(on)}$ | - | 8 | - | ns | $V_{DD}=400V, V_{GS}=10V, I_D=1.4A, R_G=12.2\Omega$; see table 10 |
| Rise time | t_r | - | 7 | - | ns | $V_{DD}=400V, V_{GS}=10V, I_D=1.4A, R_G=12.2\Omega$; see table 10 |
| Turn-off delay time | $t_{d(off)}$ | - | 40 | - | ns | $V_{DD}=400V, V_{GS}=10V, I_D=1.4A, R_G=12.2\Omega$; see table 10 |
| Fall time | t_f | - | 20 | - | ns | $V_{DD}=400V, V_{GS}=10V, I_D=1.4A, R_G=12.2\Omega$; see table 10 |

Table 6 Gate charge characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|-----------------------|---------------|--------|------|------|------|---------------------------------------------------|
| | | Min. | Typ. | Max. | | |
| Gate to source charge | Q_{gs} | - | 1.1 | - | nC | $V_{DD}=480V, I_D=1.4A, V_{GS}=0 \text{ to } 10V$ |
| Gate to drain charge | Q_{gd} | - | 5 | - | nC | $V_{DD}=480V, I_D=1.4A, V_{GS}=0 \text{ to } 10V$ |
| Gate charge total | Q_g | - | 9.4 | - | nC | $V_{DD}=480V, I_D=1.4A, V_{GS}=0 \text{ to } 10V$ |
| Gate plateau voltage | $V_{plateau}$ | - | 5.4 | - | V | $V_{DD}=480V, I_D=1.4A, V_{GS}=0 \text{ to } 10V$ |

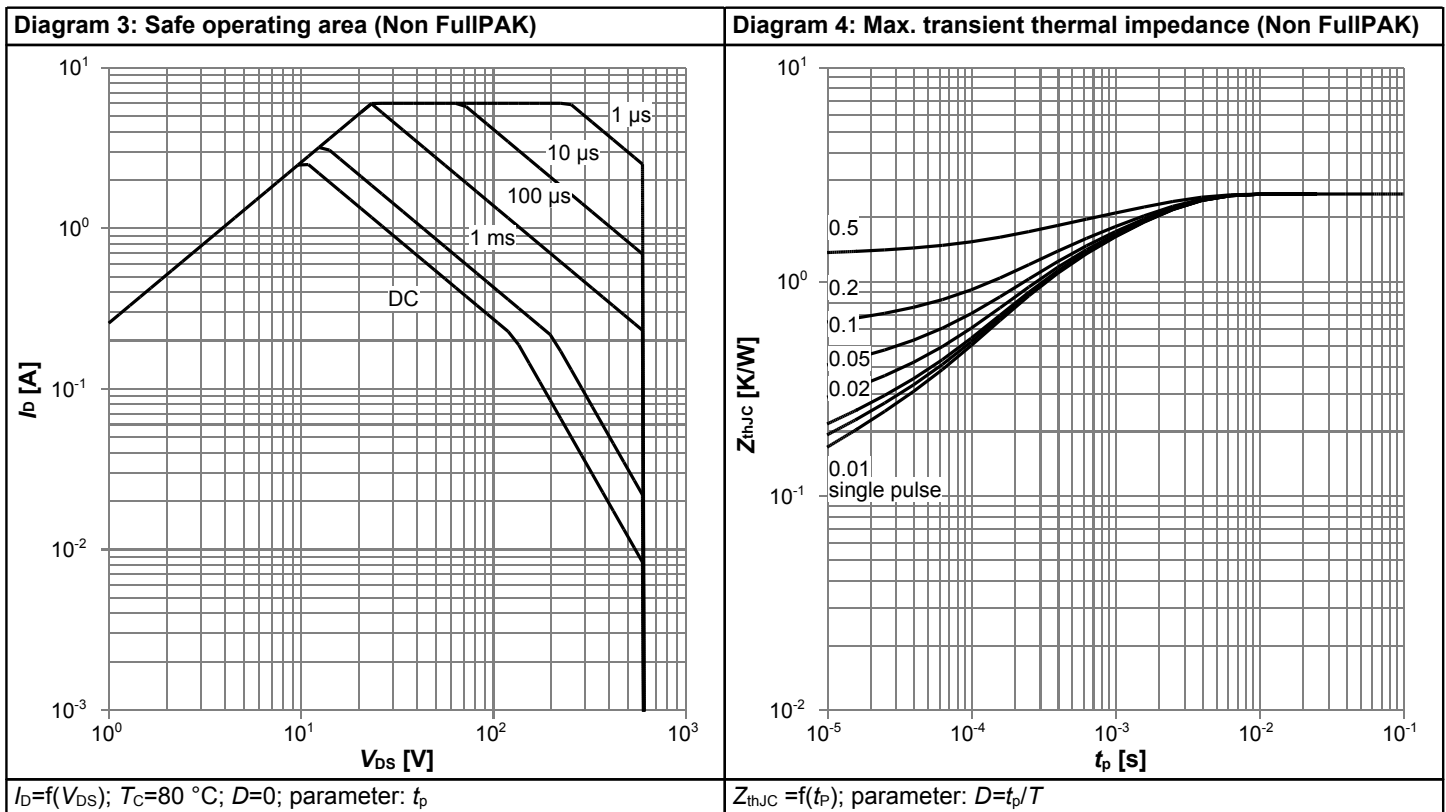
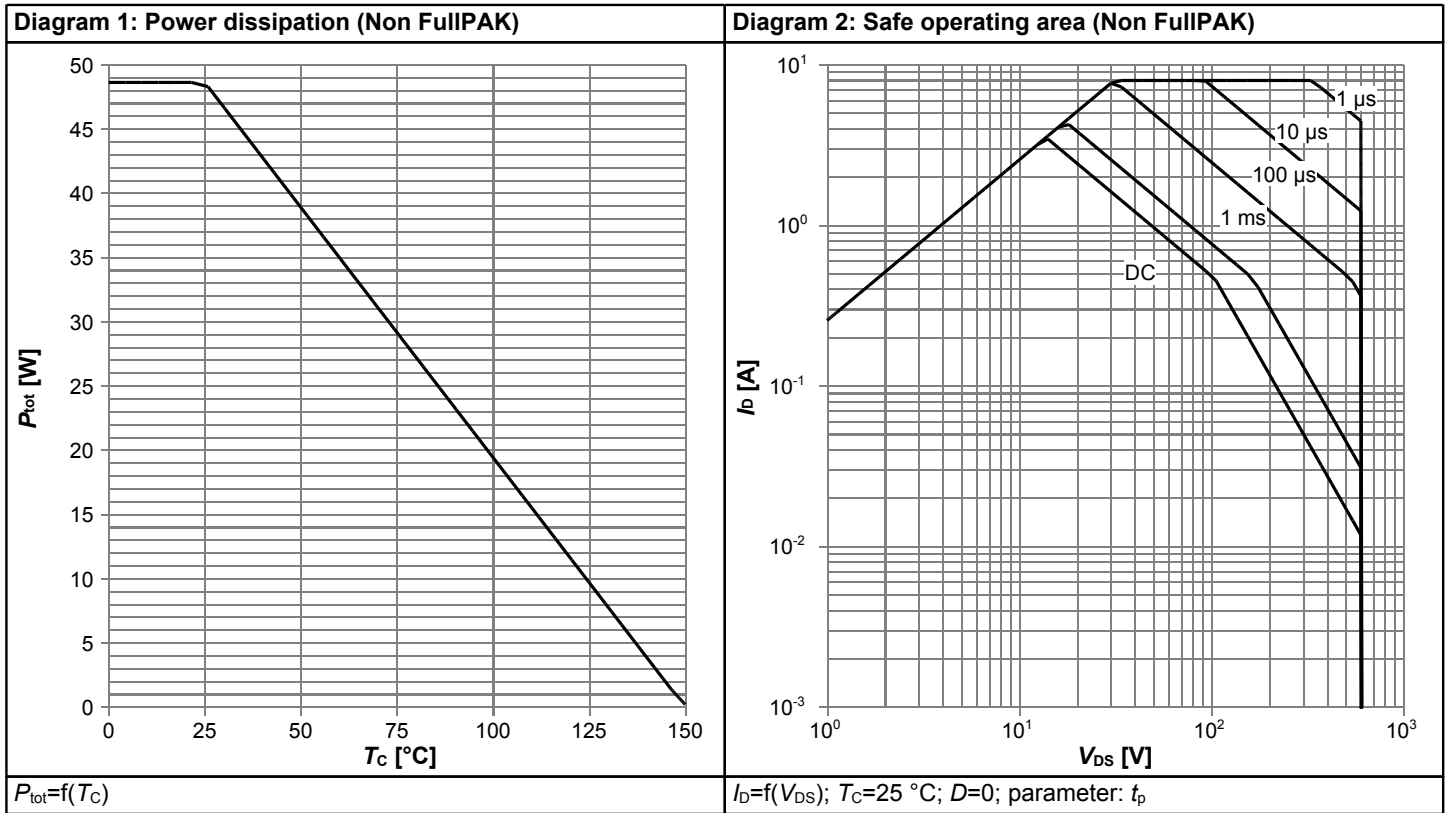
¹⁾ $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% $V_{(BR)DSS}$

²⁾ $C_{o(tr)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% $V_{(BR)DSS}$

Table 7 Reverse diode characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|-------------------------------|-----------|--------|------|------|---------|-----------------------------------------------------------|
| | | Min. | Typ. | Max. | | |
| Diode forward voltage | V_{SD} | - | 0.9 | - | V | $V_{GS}=0V, I_F=1.4A, T_j=25^\circ C$ |
| Reverse recovery time | t_{rr} | - | 230 | - | ns | $V_R=400V, I_F=1.4A, di_F/dt=100A/\mu s$; see table 9 |
| Reverse recovery charge | Q_{rr} | - | 1.1 | - | μC | $V_R=400V, I_F=1.4A, di_F/dt=100A/\mu s$; see table 9 |
| Peak reverse recovery current | I_{rrm} | - | 9.8 | - | A | $V_R=400V, I_F=1.4A, di_F/dt=100A/\mu s$; see table 9 |

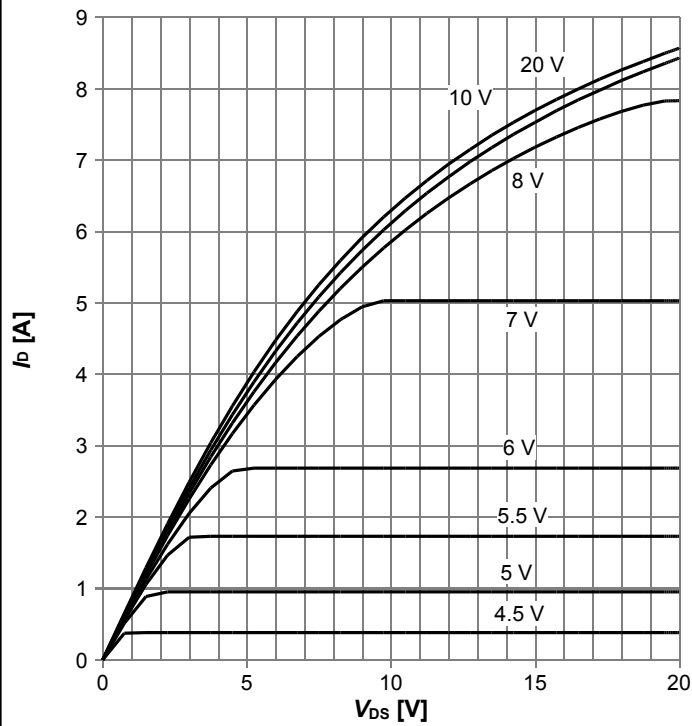
4 Electrical characteristics diagrams



600V CoolMOS™ CE Power Transistor

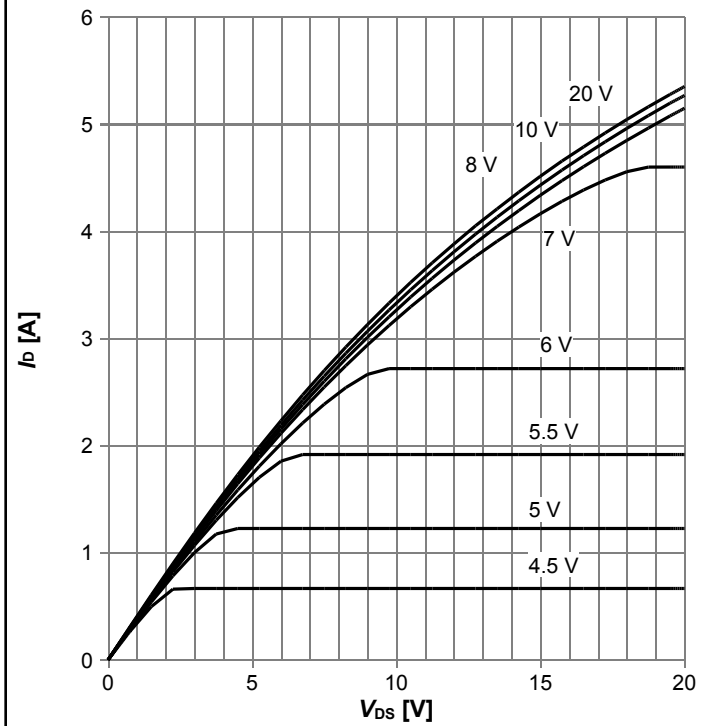
IPD60R1K5CE, IPU60R1K5CE

Diagram 5: Typ. output characteristics



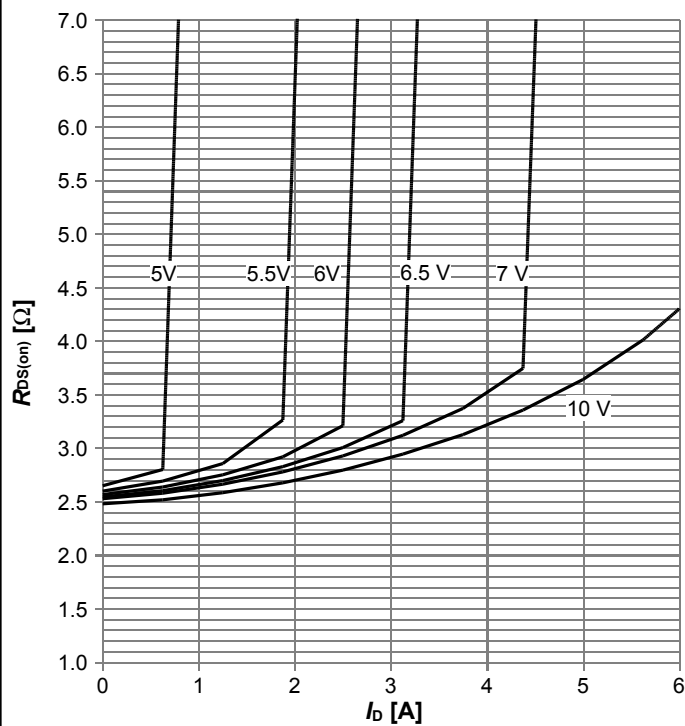
$I_D=f(V_{DS}); T_j=25\text{ }^\circ\text{C};$ parameter: V_{GS}

Diagram 6: Typ. output characteristics



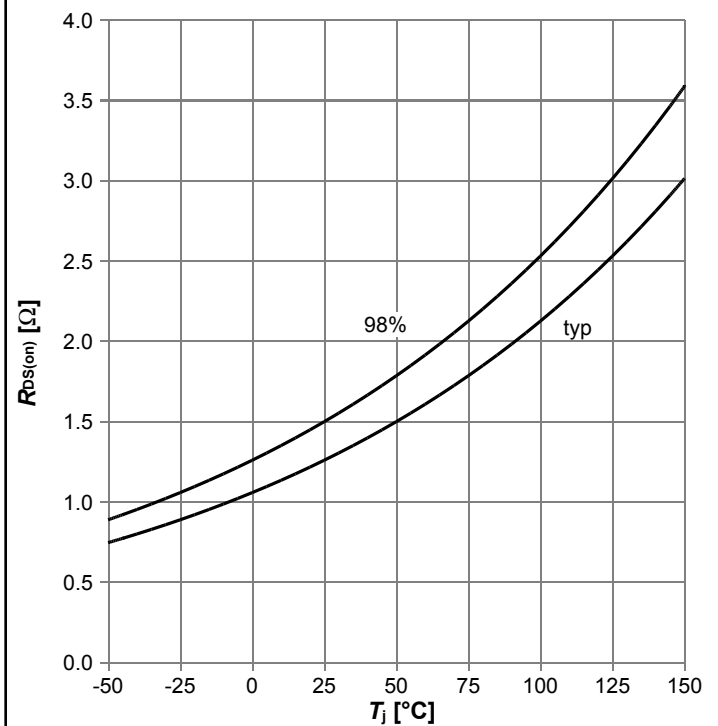
$I_D=f(V_{DS}); T_j=125\text{ }^\circ\text{C};$ parameter: V_{GS}

Diagram 7: Typ. drain-source on-state resistance



$R_{DS(on)}=f(I_D); T_j=125\text{ }^\circ\text{C};$ parameter: V_{GS}

Diagram 8: Drain-source on-state resistance

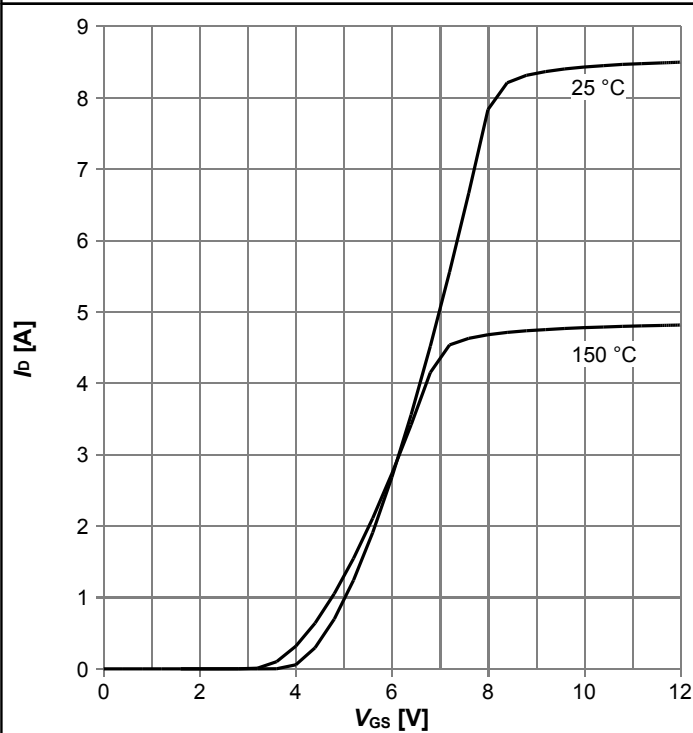


$R_{DS(on)}=f(T_j); I_D=1.1\text{ A}; V_{GS}=10\text{ V}$

600V CoolMOS™ CE Power Transistor

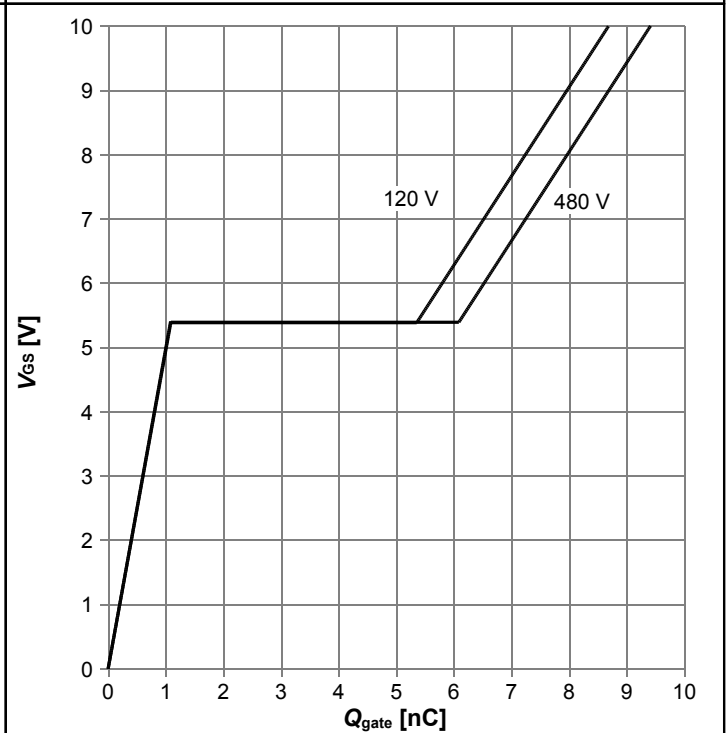
IPD60R1K5CE, IPU60R1K5CE

Diagram 9: Typ. transfer characteristics



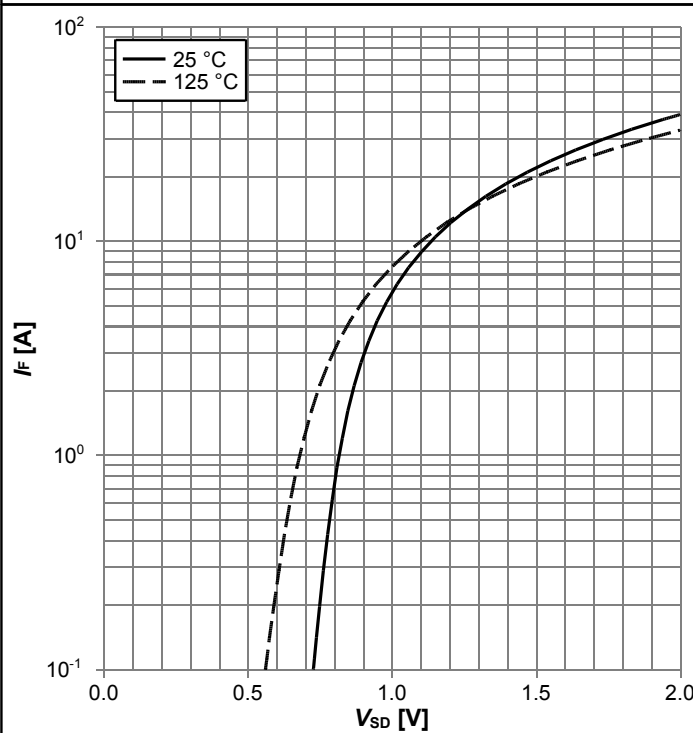
$I_D = f(V_{GS})$; $V_{DS} = 20V$; parameter: T_j

Diagram 10: Typ. gate charge



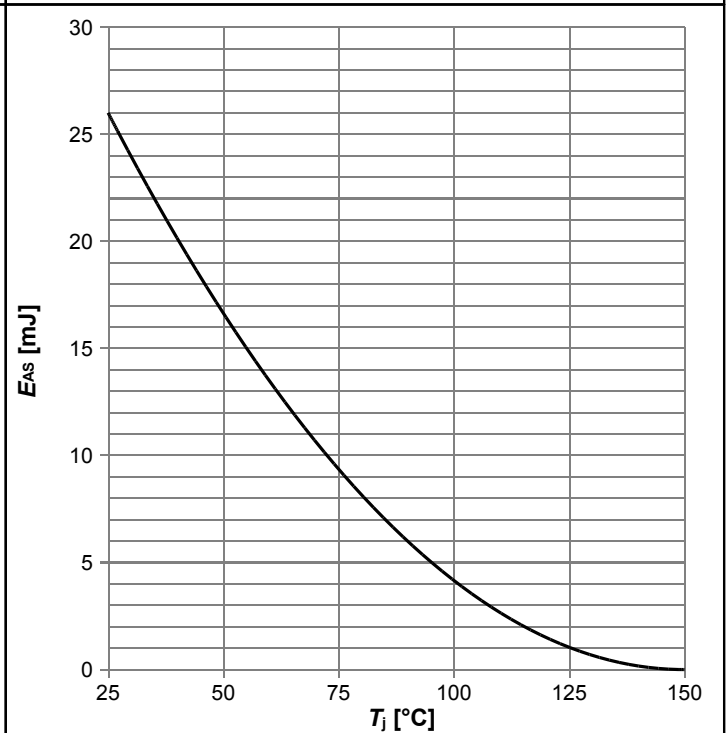
$V_{GS} = f(Q_{gate})$; $I_D = 1.4 A$ pulsed; parameter: V_{DD}

Diagram 11: Forward characteristics of reverse diode



$I_F = f(V_{SD})$; parameter: T_j

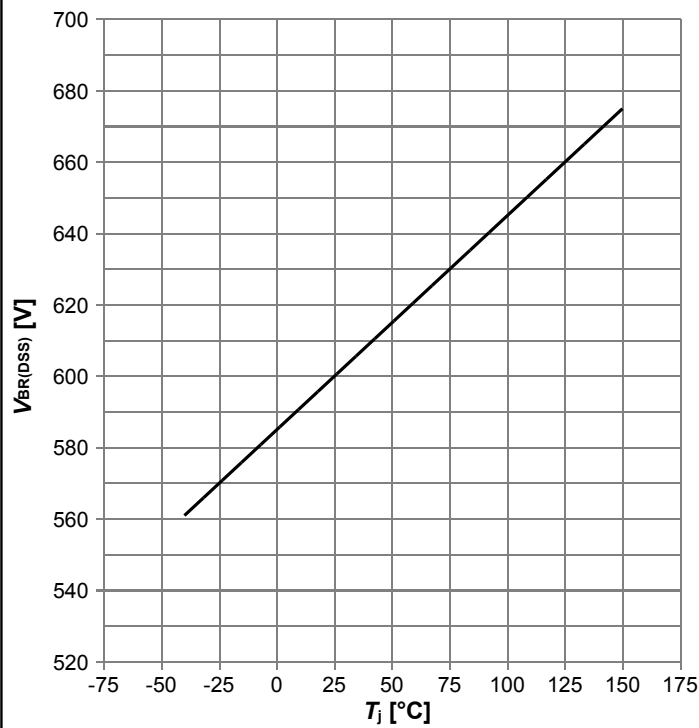
Diagram 12: Avalanche energy



$E_{AS} = f(T_j)$; $I_D = 0.6 A$; $V_{DD} = 50 V$

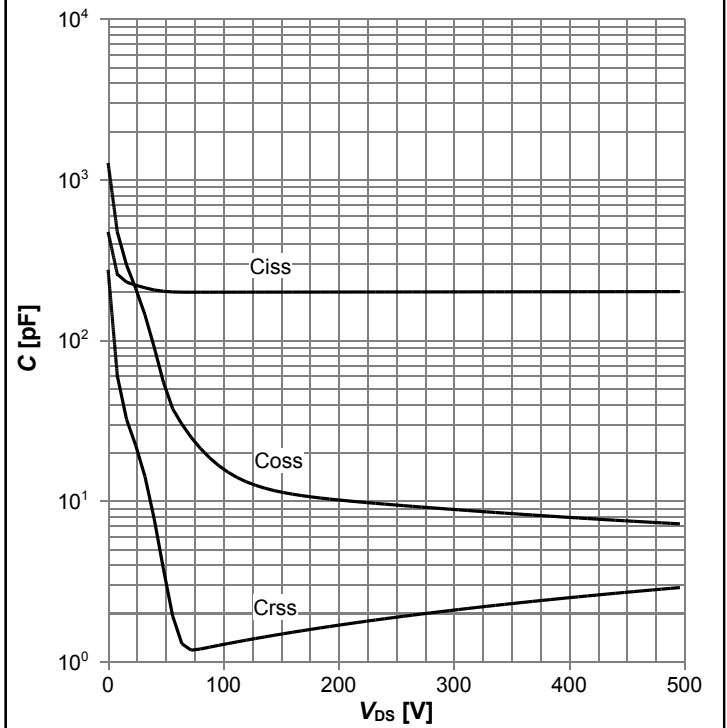
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IPD60R1K5CE, IPU60R1K5CE

Diagram 13: Drain-source breakdown voltage



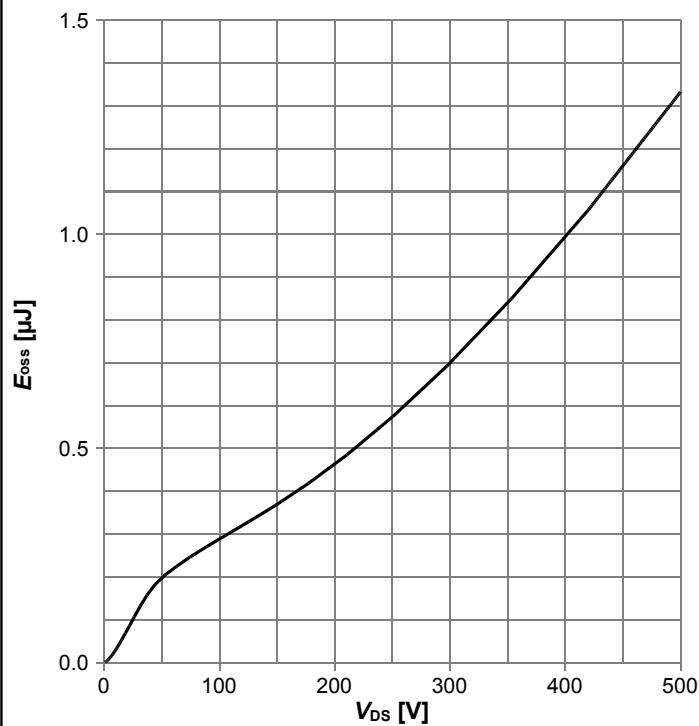
$V_{BR(DSS)}=f(T_j); I_D=0.25 \text{ mA}$

Diagram 14: Typ. capacitances



$C=f(V_{DS}); V_{GS}=0 \text{ V}; f=1 \text{ MHz}$

Diagram 15: Typ. Coss stored energy



$E_{oss}=f(V_{DS})$

5 Test Circuits

Table 8 Diode characteristics

| Test circuit for diode characteristics | Diode recovery waveform |
|----------------------------------------|-----------------------------------------------------------------------------|
| <p>$R_{g1} = R_{g2}$</p> | <p>$t_{tr} = t_F + t_S$ $Q_{tr} = Q_F + Q_S$</p> |

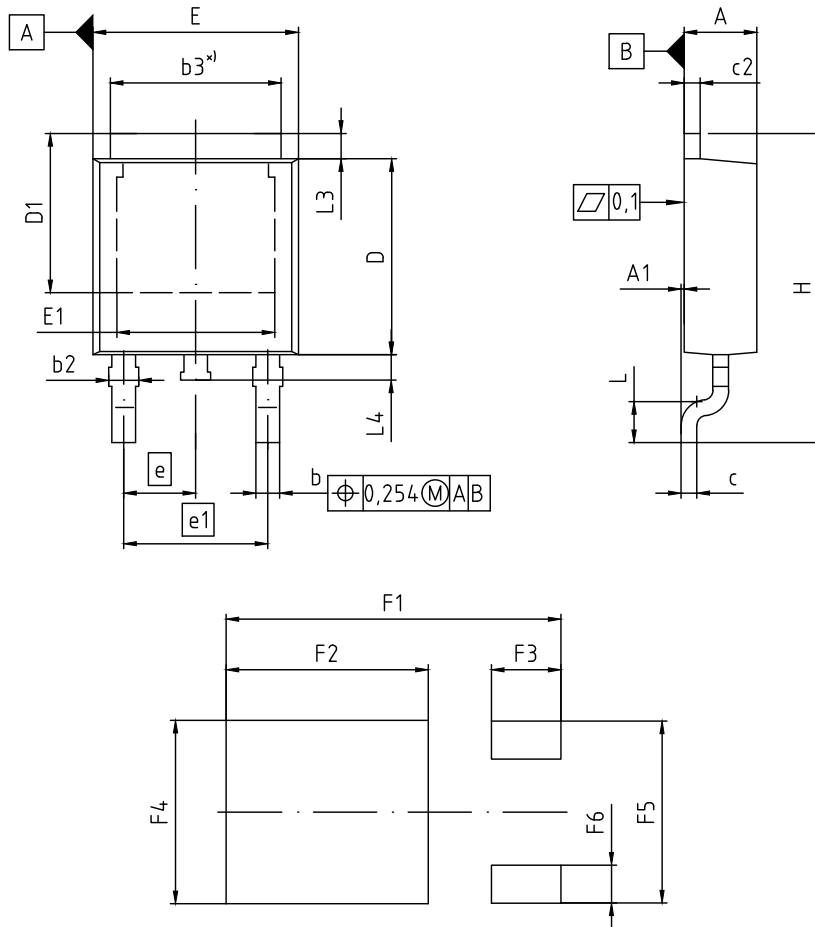
Table 9 Switching times

| Switching times test circuit for inductive load | Switching times waveform |
|-------------------------------------------------|--------------------------|
| | |

Table 10 Unclamped inductive load

| Unclamped inductive load test circuit | Unclamped inductive waveform |
|---------------------------------------|------------------------------|
| | |

6 Package Outlines



*) mold flash not included

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 2.16 | 2.41 | 0.085 | 0.095 |
| A1 | 0.00 | 0.15 | 0.000 | 0.006 |
| b | 0.64 | 0.89 | 0.025 | 0.035 |
| b2 | 0.65 | 1.15 | 0.026 | 0.045 |
| b3 | 5.00 | 5.50 | 0.197 | 0.217 |
| c | 0.46 | 0.60 | 0.018 | 0.024 |
| c2 | 0.46 | 0.98 | 0.018 | 0.039 |
| D | 5.97 | 6.22 | 0.235 | 0.245 |
| D1 | 5.02 | 5.84 | 0.198 | 0.230 |
| E | 6.40 | 6.73 | 0.252 | 0.265 |
| E1 | 4.70 | 5.60 | 0.185 | 0.220 |
| e | 2.29 (BSC) | | 0.090 (BSC) | |
| e1 | 4.57 (BSC) | | 0.180 (BSC) | |
| N | 3 | | 3 | |
| H | 9.40 | 10.48 | 0.370 | 0.413 |
| L | 1.18 | 1.70 | 0.046 | 0.067 |
| L3 | 0.90 | 1.25 | 0.035 | 0.049 |
| L4 | 0.51 | 1.00 | 0.020 | 0.039 |
| F1 | 10.60 | | 0.417 | |
| F2 | 6.40 | | 0.252 | |
| F3 | 2.20 | | 0.087 | |
| F4 | 5.80 | | 0.228 | |
| F5 | 5.76 | | 0.227 | |
| F6 | 1.20 | | 0.047 | |

| |
|------------------------------------|
| DOCUMENT NO. Z8B00003328 |
| SCALE 0 2.0 4mm |
| EUROPEAN PROJECTION |
| ISSUE DATE 01-09-2015 |
| REVISION 05 |

Figure 1 Outline PG-TO 252, dimensions in mm/inches

600V CoolMOS™ CE Power Transistor
IPD60R1K5CE, IPU60R1K5CE

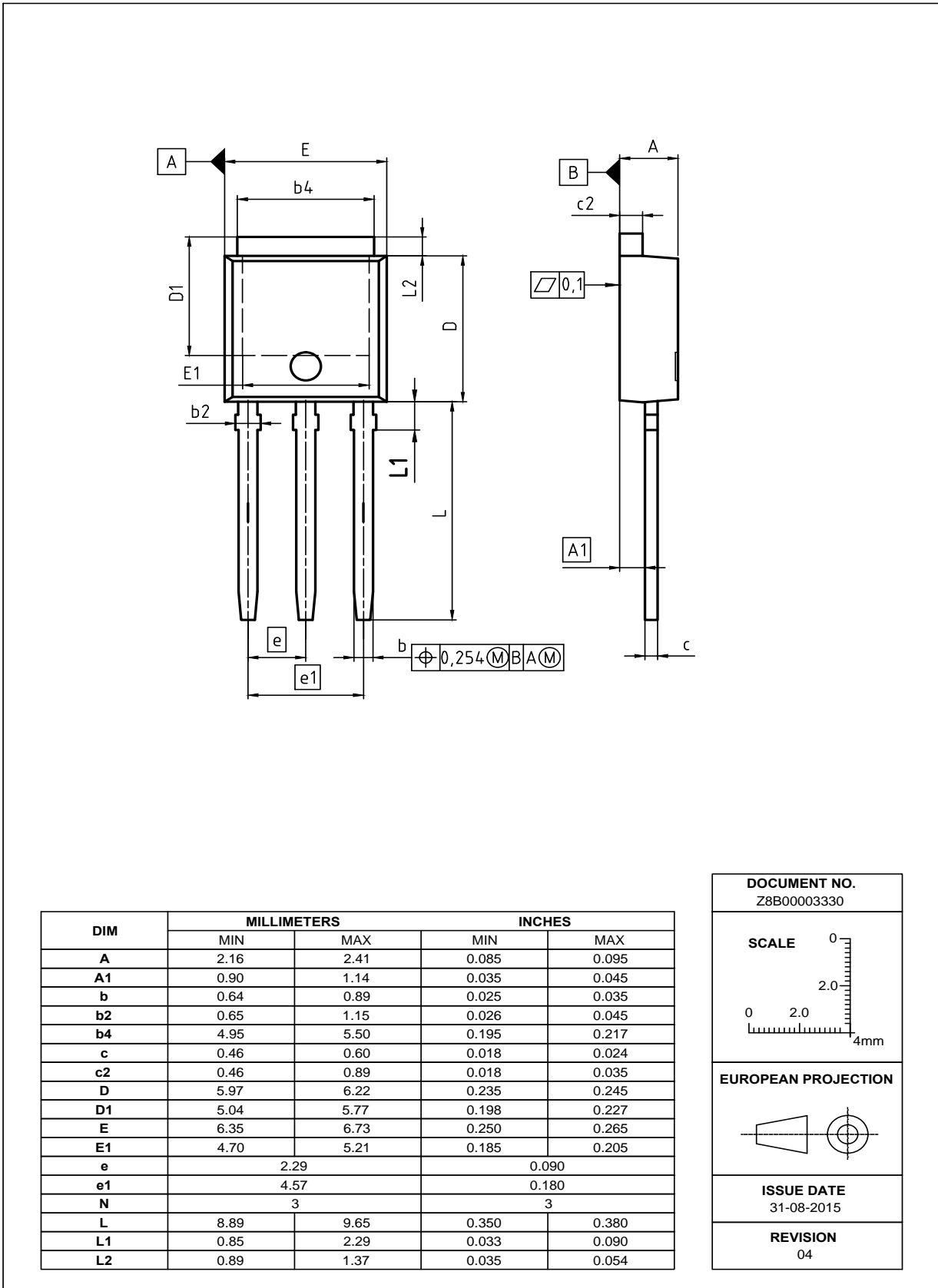


Figure 2 Outline PG-TO 251, dimensions in mm/inches

7 Appendix A

Table 11 Related Links

- IFX CoolMOS™ CE Webpage: www.infineon.com
- IFX CoolMOS™ CE application note: www.infineon.com
- IFX CoolMOS™ CE simulation model: www.infineon.com
- IFX Design tools: www.infineon.com

Revision History

IPD60R1K5CE, IPU60R1K5CE

Revision: 2016-03-31

Previous Revision

| Date | Subjects (major changes since last revision) |
|------------|-------------------------------------------------------------------|
| 2014-09-25 | Release of final version |
| 2015-11-17 | Updated to qualified for standard grade & updated package drawing |
| 2016-03-31 | Modified Id, Rthjc. Modified SOA, Zthjc curves |

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